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1 - 11. (Canceled)

12. (Previously Canceled)

13-18. (Canceled)

19. (New) A method of manufacturing an information handling system, comprising:

manufacturing a lower chassis having a housing, a motherboard, memory, a plurality of expansion drive bays, and a connector for connection to an external supply of DC power, wherein the motherboard, the memory, and the plurality of expansion drive bays are connected to the housing of the lower chassis;

manufacturing an upper chassis having a housing, a display, and a power supply, wherein the upper chassis is manufactured at a different location than the lower chassis, and wherein the display and the power supply are connected to the housing of the upper chassis, wherein the upper chassis is manufactured to be disposed on top of the lower chassis, and wherein the lower chassis is manufactured to be disposed beneath the upper chassis; and

shipping the lower and the upper chassis directly to a customer without pre-assembly of the upper and lower chassis, wherein the shipping of either the upper or the lower chassis avoids import and export tariffs associated with shipping the entire information handling system.

20. (New) The method of claim 19, wherein the lower chassis further has a lower chassis blind mate connector.

21. (New) The method of claim 20, wherein the upper chassis further has an upper chassis blind mate connector.

22. (New) The method of claim 21, wherein the lower and upper chassis are connectable by the upper and lower chassis blind mate connectors to pass signals therebetween.

23. (New) The method of claim 22, wherein the lower and upper chassis are only operational when connected via the upper and lower chassis blind mate connectors.

24. (New) The method of claim 19, wherein the lower chassis has a plurality of guide pins extending therefrom, and wherein the upper chassis has a plurality of mating guide pin openings for connecting the upper and lower chassis.

25. (New) The method of claim 21, wherein the upper chassis further comprises an AC to DC power converter, and the upper chassis blind mate connector is for passing only DC power to the lower chassis.

26. (New) The method of claim 19, wherein manufacturing the lower chassis further comprises: manufacturing the lower chassis to fit substantially flush with the upper chassis.

27. (New) The method of claim 19, wherein manufacturing the upper chassis further comprises: manufacturing the upper chassis to fit substantially flush with the lower chassis.

28. (New) The method of claim 19, wherein the import and export tariffs are avoided by neither the upper chassis nor the lower chassis alone being classified as a computer.

29. (New) The method of claim 19, wherein the upper chassis and lower chassis are connectable without cabling.

30. (New) A method of manufacturing an information handling system, comprising:

manufacturing a lower chassis having a housing, a motherboard, memory, a plurality of expansion drive bays, and a connector for connection to an external supply of DC power, wherein the motherboard, the memory, and the plurality of expansion drive bays are connected to the housing of the lower chassis;

manufacturing an upper chassis having a housing, a display, and a power supply, wherein the upper chassis is manufactured at a different location than the lower chassis, and wherein the display and the power supply are connected to the housing of the upper chassis, wherein the upper chassis is manufactured to be disposed on top of the lower chassis, and wherein the lower chassis is manufactured to be disposed beneath the upper chassis; and

shipping the lower and the upper chassis directly to a customer without pre-assembly of the upper and lower chassis, wherein shipping the lower and upper chassis directly from the manufacturing location reduces shipping costs when the lower and upper chassis are manufactured at different locations.

31. (New) The method of claim 30, wherein the lower chassis further has a lower chassis blind mate connector.

32. (New) The method of claim 31, wherein the upper chassis further has an upper chassis blind mate connector.

33. (New) The method of claim 32, wherein the lower and upper chassis are connectable by the upper and lower chassis blind mate connectors to pass signals therebetween.

34. (New) The method of claim 33, wherein the lower and upper chassis are only operational when connected via the upper and lower chassis blind mate connectors.

35. (New) The method of claim 30, wherein the lower chassis has a plurality of guide pins extending therefrom, and wherein the upper chassis has a plurality of mating guide pin openings for connecting the upper and lower chassis.

36. (New) The method of claim 32, wherein the upper chassis further comprises an AC to DC power converter, and the upper chassis blind mate connector is for passing only DC power to the lower chassis.

37. (New) The method of claim 30, wherein manufacturing the lower chassis further comprises: manufacturing the lower chassis to fit substantially flush with the upper chassis.

38. (New) The method of claim 30, wherein manufacturing the upper chassis further comprises: manufacturing the upper chassis to fit substantially flush with the lower chassis.